

# Accelerated Graphics Port (AGP) Connectors

### Description:

Connector for AGP video cards

### Typical Applications:

- Desktop computers
- Workstations
- Servers

### Benefits/Features:

Industry Standard . . . Meets AGP Implementer's Forum specification mating requirements. Supports high performance 3D graphics cards.

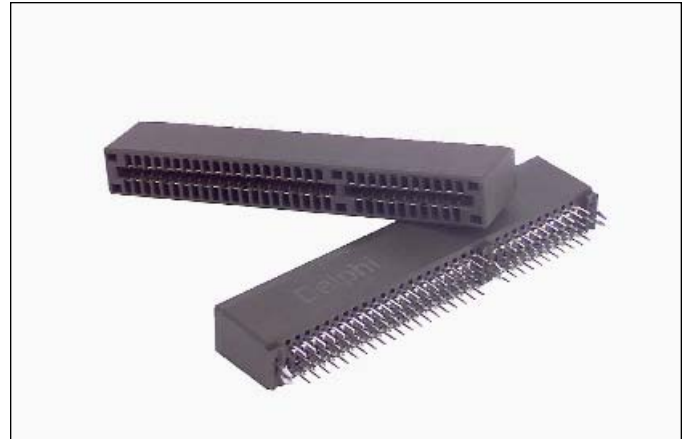
Flexible System . . . . Meets speed requirements of AGP 1x, 2x and 4x.

Ruggedness . . . . . Metal board locks hold connector securely during PCB processing.

Reliability . . . . . Several gold plating options are available for improved reliability. Low mating force through staggered mating contacts.

### Selectable Features:

Product Type	AGP edge card
Total No. of Positions	124
Centerline Spacing	1.00 mm [.039 in.]
Orientation	Vertical
Mounting Style	Board through-hole
Voltage	0.8 V, 1.5 V, 3.3 V
PCB Thickness	1.57 mm [.062 in.]
Insertion Style	Direct
Contact Style	Formed
Contact Area Plating	0.2 $\mu$ m [8 $\mu$ in.] gold
Height Above Board	15.40 mm [.61 in.]
Tail Length	2.60 mm [.102 in.] or 3.10 mm [.122 in.]
Hold Down Material	Bronze alloy
Housing Color	Brown



### Other Properties:

Packaging Type	Tubes or tray
Housing Material	GF PBT
Applicable Soldering Process	IR, vapor phase, wave
Contact Base Material	Phosphor bronze
Insulation Resistance	800 M $\Omega$
Withstanding Voltage	400 VAC RMS
Current Rating	1 amp max. per contact
Contact Resistance	30 m $\Omega$
Voltage Rating	150 or 250 VAC/DC
Temperature Range	-20°C to +100°C
Continuous Operating Temperature	-0°C to +85°C
Normal Force	0.29 N [30 gf] min.
Contact Retention Force	6.67 N [1.5 lbf]
Durability (Mating Cycles)	50 cycles
Mating Force	56.9 N [12.8 lbf] max.
Unmating Force	34.3 N [7.7 lbf] min.
Plating (Contact Area)	Gold (thickness varies per Delphi spec.) over nickel underplating
Plating (Soldering End)	2.54 $\mu$ m [100 $\mu$ in.] tin-lead over nickel underplating
Underplating	1.27 $\mu$ m [50 $\mu$ in.] nickel
Standards	Accelerated graphics port interface specification
Approvals and Certification	UL approved

# Accelerated Graphics Port (AGP) Connectors

## Ordering Nomenclature

15430314 - **1** **1** **0**

### Selective Plating:

Gold plated on contact area and 2.54  $\mu\text{m}$  [100  $\mu\text{in.}$ ] min. tin-lead plated on soldering end over 1.27  $\mu\text{m}$  [50  $\mu\text{in.}$ ] min. nickel underplating

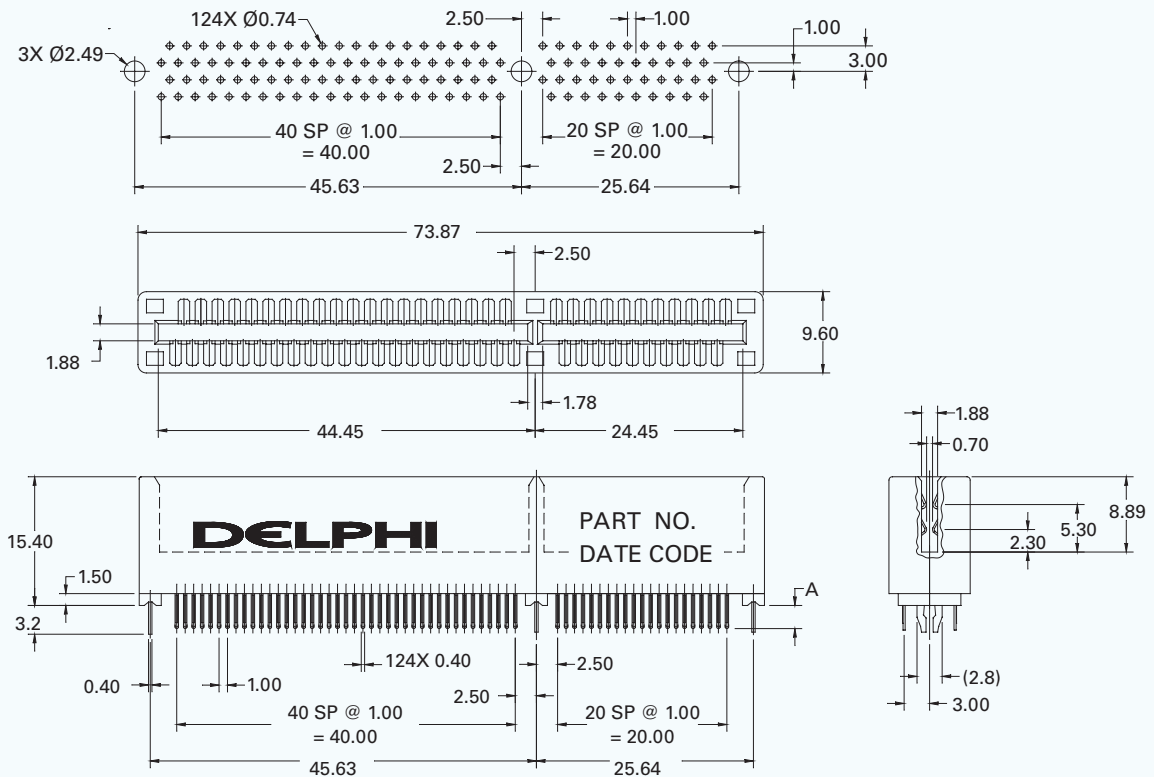
- 1 = Gold Flash
- 2 = 0.381  $\mu\text{m}$  [15  $\mu\text{in.}$ ]
- 3 = 0.762  $\mu\text{m}$  [30  $\mu\text{in.}$ ]

0 = N/A

### DIM "A" - Solder Tail Length:

- 1 = 2.60 mm [.102 in.]
- 2 = 3.10 mm [.122 in.]

## PC Board Layout



Unless otherwise specified, dimensions are shown in millimeters.

# DELPHI

[www.delphi.com/connect](http://www.delphi.com/connect)

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